

Bondline

Application Instructions

For maximum bond strength and optimal thermal efficiency Universal Science has prepared this application procedure guide for our range of Bondline thermally conductive, adhesive tapes. The below steps must be followed to achieve the best application results. Our recommended tape application temperature is between 68°F and 80.6°F.

Application Procedure

1. Ensure both mating surfaces are clean, free of any contaminants such as dust or oil and free of fingerprints. Surfaces can be cleaned with an isopropyl alcohol (IPA), lint-free cloth to fully guarantee the removal of contaminants. Both surfaces must be completely dry before tape application. To avoid further contact with the surface to be bonded with, wear suitable gloves.
2. Ensure tape is free of dust and any other contaminants
3. Slowly peel the liner from one side to expose the adhesive, make sure no skin contact is made with the exposed adhesive as this will result in skin oil deposits.
4. Inspect the tape and apply to the surface with moderate compression pressure for a minimum of 5 seconds. To avoid air entrapments during tape application, apply even pressure by using a rubber roller for smooth application.
5. Once the tape has been fixed remove the second carrier liner and position the electronic device accurately. Apply moderate pressure to the assembly to ensure good adhesion and adhesive wetting of both contact surfaces that have been bonded.
6. Bondline tapes achieve 2/3's of their ultimate bonding strength within the first 24 hours of application. If the tape, for any reason, needs to be removed from the surface do not reuse the original piece. Replace with a new one.

N.B. For single lined Bondline 700, such as when supplied on a roll, after step 1 apply tape direct from roll to surface and continue from step 4.



www.universal-science.com

UK  +44 (0) 1908 222 211

IT  +39 (02) 395 613 61 FR  +33 (0) 1602 00276